Soldering Temperature	T_{sol}	260	

NOTE1 í ì ì … • ‰ µì ð ,•(Œ ‹ µ v Ç

NOTE2 (} Œ í u] v µ š U Z X , X A ð ì • ò ì 9

ELECTRICAL CHARACTERISTICS (Temperature = 25 Á C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	¥	I_F = 10mA	-	1.8	2.5	V
	Reverse Current	ł	V_R = 6V	-	-	1	ε A
	Input Capacitance	Ğ	V = 0V f = 1M H z	-	70	-	pF
Detector	Off-state Current	I_{OFF}	V_{OFF} = 100V	-	-	10	nA
	Output Capacitance	C_{OFF}	V = 0V f = 1M H z t < 1s	-	170	-	pF
Coupled	Trigger LED Current	I_{FT}	I_{ON} = 2A	-	0.35	1	mA
	Return LED Current	I_{FC}	I_{OFF} = 10 ε A	0.1	0.8	-	mA
	On-state Resistance	R_{ON}	I_{ON} = 2A I_F = 5mA t < 1s	-	0.5	1	q
Switching Characteristics	Isolation Resistance	R_{ISO}	DC500V 40 ~ 60%R. H .	-	10^{14}	-	q
	Turn On Time	t					

ORDERING INFORMATION

J OF M A D E G - P S 4 C)

Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

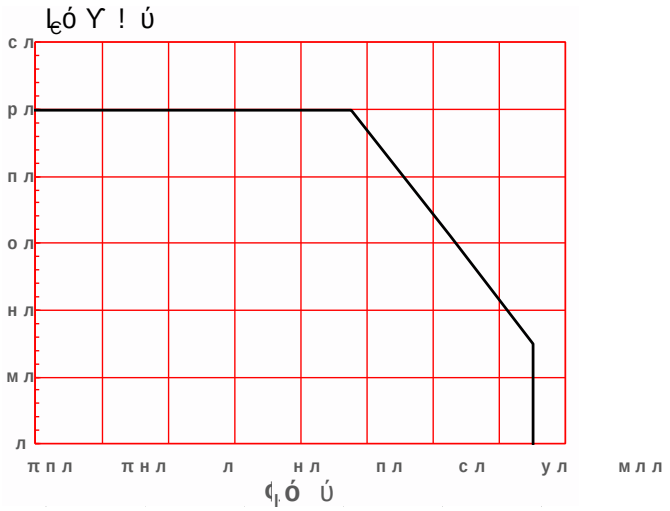


FIG.2: On-state Current vs. Ambient Temperature

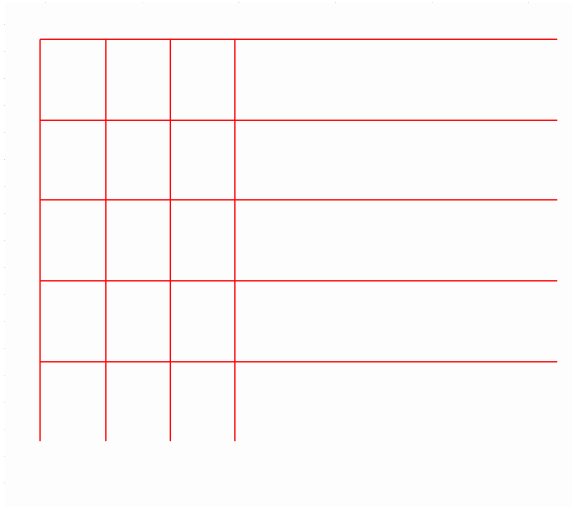


FIG.7: T_{ON},T_{OFF} vs. LED Forward Current

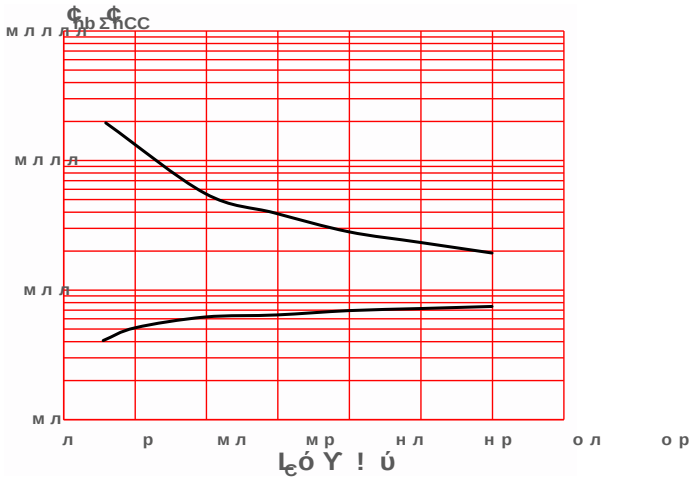
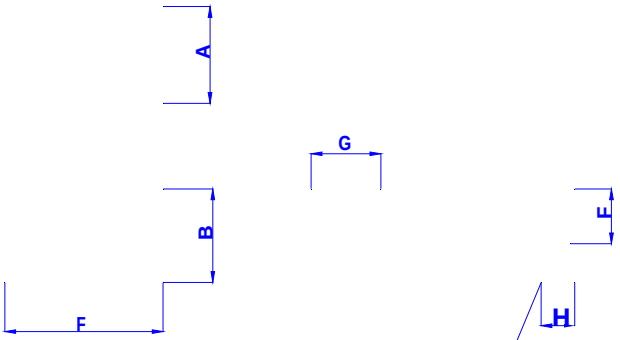


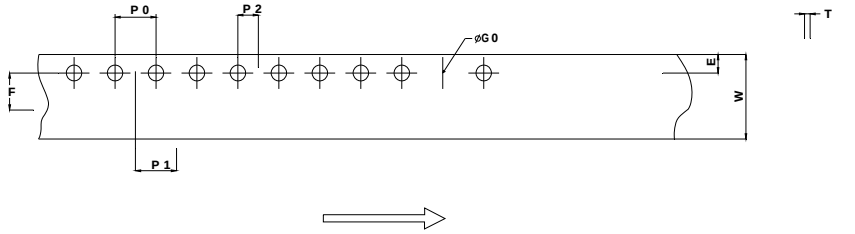
FIG.8: T_{ON},T_{OFF} vs. Ambient Temperature

Package Dimension (Unit: mm)



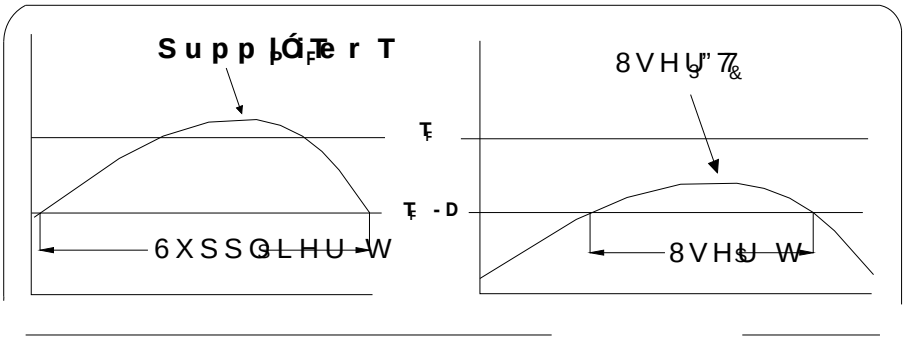
Ref	Gimensions					
	MillimePers			HncOes		
	Min	Typ	MMx	Min	Typ	MMx
A	1B30		1B70	0B0D1		0B067
B	1BE0		2B30	0B07D		0B0E1
F	3B20		3B60	0B126		0B142
G	0B88		1B28	0B03D		0B0D0
E	2B1D		2BDD	0B08D		0B100
F	1B00		1B40	0B03E		0B0DD
G	0B20		0B60	0B008		0B024
H	0B6D		-	ŮŮ		

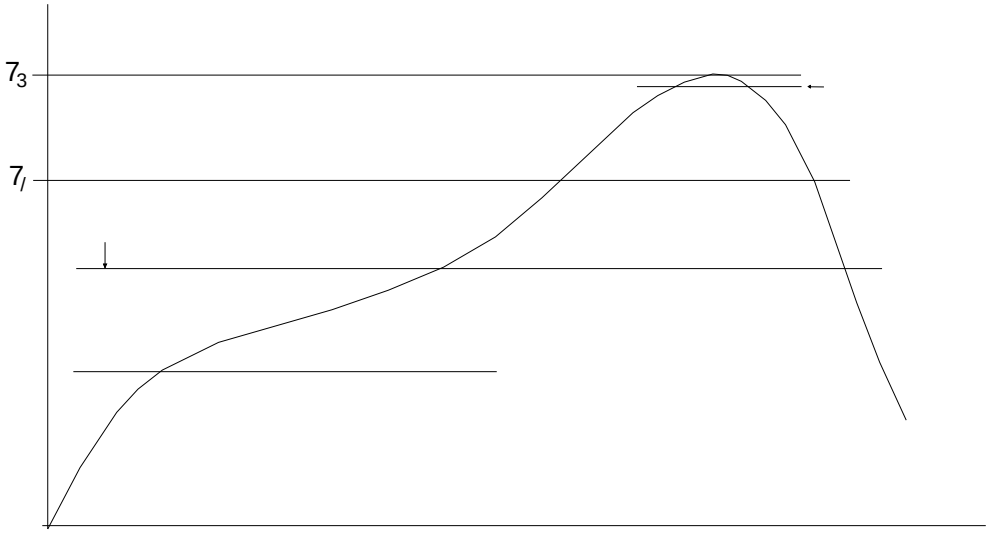
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



Ref	Gimensions					
	MillimePers			HncOes		
	Min	Typ	MMx	Min	Typ	MMx
G0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	3.90	4.00	4.10	0.154	0.157	0.161
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	3.45	3.50	3.55	0.136	0.138	0.142
T	0.25	0.25	0.30	0.008	0.010	0.012
W	7.70	8.00	8.30	0.303	0.315	0.327

REFLOW INFORMATION





Note:

1. Reflow soldering is recommended at the temperatures and time shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0 ~ 40 Á C ;

Recommend storage humidity: < 60% ;

MSL level: MSL 3